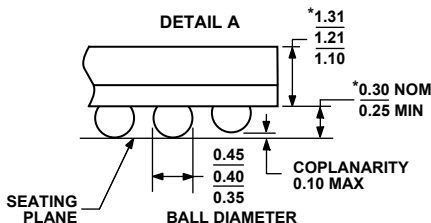
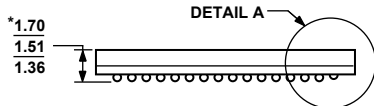
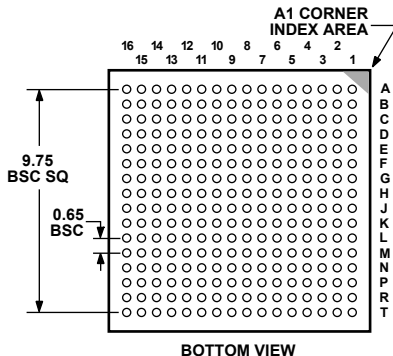
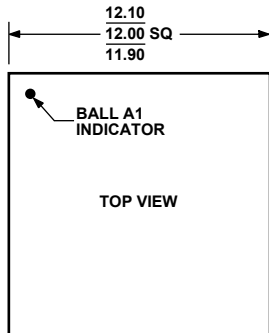


256-Lead Chip Scale Package Ball Grid Array [CSP_BGA]

(BC-256-1)

Dimensions shown in millimeters

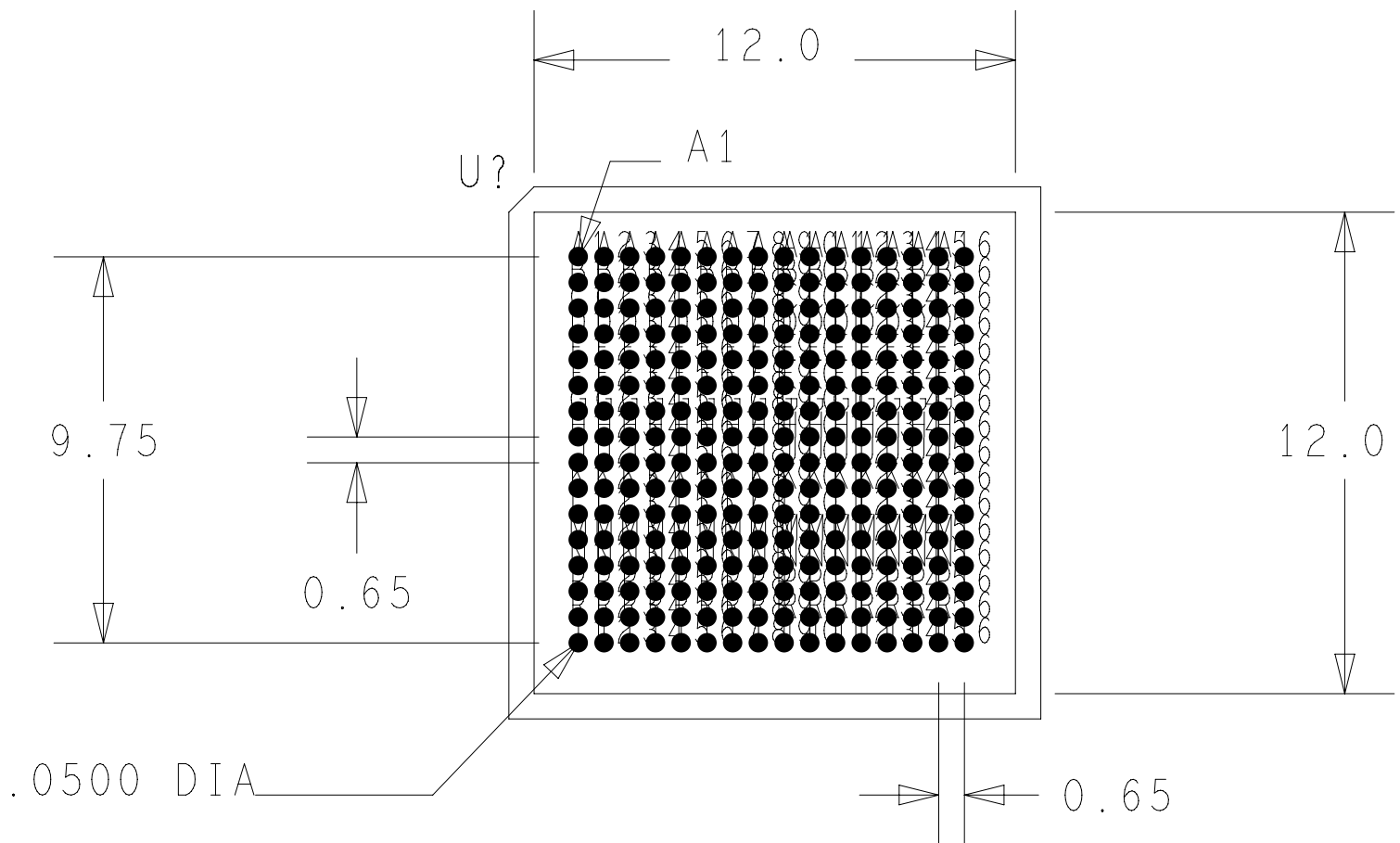


*COMPLIANT TO JEDEC STANDARDS MO-225 WITH EXCEPTION
TO DIMENSIONS INDICATED BY AN ASTERISK.

Analog Devices

BC - 256 - 1

REV A



(Dim. are in MM)

LAST MODIFIED 09/12/07